

WIN*SOURCE*
ELECTRONICS

THE DATASHEET OF
1612507-3



1612507-3 ✓ ACTIVE

DDR SODIMM, DDR2 SO DIMM

TE Internal #: 1612507-3

Double Data Rate (DDR), Stack Height 5.2 mm [.205 in], Right Angle

Module Orientation, 200 Position, DDR SODIMM, SO DIMM

Sockets

[View on TE.com >](#)



[Connectors](#) > [Socket Connectors](#) > [Memory Sockets](#) > [SO DIMM Sockets](#) > [DDR2 SO DIMM Sockets](#)



DRAM Type: **Double Data Rate (DDR)**

Stack Height: **5.2 mm [.205 in]**

Module Orientation: **Right Angle**

Number of Positions: **200**

Centerline (Pitch): **.6 mm [.024 in]**

[All DDR2 SO DIMM Sockets \(30\)](#)

Features

Product Type Features

Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR)

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200

Electrical Characteristics

DRAM Voltage	2.5 V
--------------	-------

Signal Characteristics



SGRAM Voltage	2.5 V
---------------	-------

Body Features

Ejector Location	Both Ends
------------------	-----------

Retention Post Material	Copper Alloy
-------------------------	--------------

Latch Material	Stainless Steel
----------------	-----------------

Latch Plating Material	Tin
------------------------	-----

Module Key Type	SGRAM
-----------------	-------

Ejector Type	Locking
--------------	---------

Connector Profile	Standard
-------------------	----------

Contact Features

Memory Socket Type	Memory Card
--------------------	-------------

PCB Contact Termination Area Plating Material	Gold Flash
---	------------

Contact Base Material	Copper Alloy
-----------------------	--------------

Contact Current Rating (Max)	.5 A
------------------------------	------

Contact Mating Area Plating Material	Gold Flash
--------------------------------------	------------

Termination Features

Insertion Style	Cam-In
-----------------	--------

Termination Method to PCB	Surface Mount
---------------------------	---------------

Mechanical Attachment

Mating Alignment Type	Standard Keying
-----------------------	-----------------

PCB Mount Retention	With
---------------------	------

PCB Mount Retention Type	Solder Tail
--------------------------	-------------

Connector Mounting Type	Board Mount
-------------------------	-------------

Housing Features

Housing Material	High Temperature Thermoplastic
------------------	--------------------------------

Housing Color	Black
---------------	-------

Centerline (Pitch)	.6 mm [.024 in]
--------------------	-----------------

Dimensions

Stack Height	5.2 mm [.205 in]
--------------	------------------

Row-to-Row Spacing	6.2 mm [.244 in]
--------------------	------------------

Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
-----------------------------	----------------------------



Operation/Application

Circuit Application	Power
---------------------	-------

Industry Standards

UL Flammability Rating	UL 94V-0
------------------------	----------

Packaging Features

Packaging Quantity	16
Packaging Method	Hard Tray

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

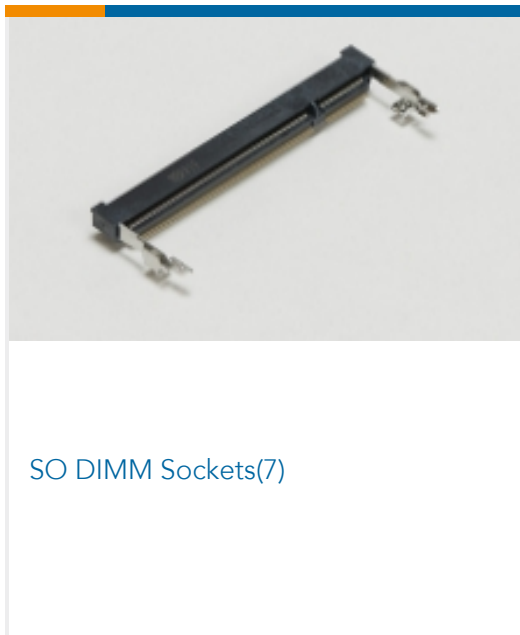
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

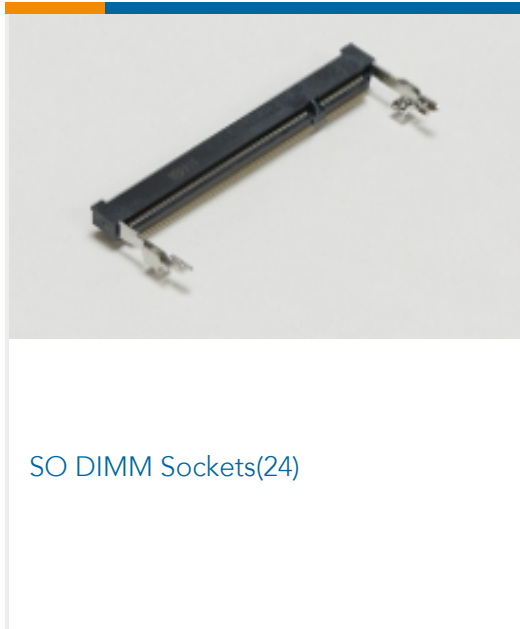
Compatible Parts



Also in the Series | DDR SODIMM



Also in the Series | DDR2 SO DIMM



Customers Also Bought





Documents

Product Drawings

HARD TRAY ASS'Y DDR SODIMM SOC

English

CAD Files

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.2d_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1612507-3_D1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

[View 1612507-3 on WIN SOURCE](#)

[TE Connectivity Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management